



Product Change Notification: NTDO-07FWSK949

Date:

12-Oct-2025

Product Category:

Digital Temperature Sensors, Memory

Notification Subject:

CCB 7877 Final Notice: Qualification of 558-2C31 as a new die attach material, G700LTD as a new molding compound material and CuPdAu as an additional wire material for 24AA044T-E/MUY, 24AA044T-I/MUY, 34AA04T-E/MUY, 34AA04T-I/MUY, 34AA04T-I/MUY-MIC, MCP98243T-BE/MUY and MCP98243T-BE/MUYAA catalog part numbers (CPN) available in 8L UDFN (2x3x0.5mm) package.

Affected CPNs:

[NTDO-07FWSK949_Affected_CPN_10122025.pdf](#)

[NTDO-07FWSK949_Affected_CPN_10122025.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of 558-2C31 as a new die attach material, G700LTD as a new molding compound material and CuPdAu as an additional wire material for 24AA044T-E/MUY, 24AA044T-I/MUY, 34AA04T-E/MUY, 34AA04T-I/MUY, 34AA04T-I/MUY-MIC, MCP98243T-BE/MUY and MCP98243T-BE/MUYAA catalog part numbers (CPN) available in 8L UDFN (2x3x0.5mm) package.

Pre and Post Summary Changes:

	Pre Change	Post Change
Assembly Site	UTAC Thai Limited (UTL-1) LTD. (NSEB)	UTAC Thai Limited (UTL-1) LTD. (NSEB)

Wire Material	Au	Au
Die Attach Material	8200T (PFAS)	558-2C31 (PFAS-free)
Molding Compound Material	G770HCD	G700LTD
Lead-Frame Material	C7025	EFTEC-64T
DAP Surface Prep	NiPdAu	Bare copper

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying 558-2C31 as a new die attach material, G700LTD as a new molding compound material and EFTEC-64T as a new leadframe material to standardize the use of PFAS free material.

Change Implementation Status: In Progress

Estimated First Ship Date: 30 October 2025 (date code: 2544)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	October 2025				
Work Week	40	41	42	43	44
Qual Report Availability		x			
Final PCN Issue Date		x			
Estimated Implementation Date					x

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as

PCN_#_Qual_Report.

Revision History: October 12, 2025: Issued final notification

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PFAS Elimination and Die Attach_Explanation.pdf
PCN_NTDO-07FWSK949_Qual_Report.pdf
PCN_NTDO-07FWSK949_Pre and Post Change_Summary.pdf

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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